

**RESPONSE UNDER 37 C.F.R. § 1.116  
EXPEDITED PROCEDURE  
EXAMINING GROUP 2800**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	T. Haze	Attorney Docket No.: LEPA122745
Application No.:	10/823,297	Art Unit: 2822 / Confirmation No: 4560
Filed:	April 13, 2004	Examiner: P.E. Perkins
Title:	METHOD OF FORMING BUMP PAD OF FLIP CHIP AND STRUCTURE THEREOF	

RESPONSE UNDER 37 C.F.R. § 1.116

Seattle, Washington 98101

June 7, 2007

TO THE COMMISSIONER FOR PATENTS:

This paper is filed in response to the final Office Action mailed on March 8, 2007. Currently Claims 1-9 are pending in the application. Of these, Claims 7-9 are withdrawn from consideration as being directed to a distinct invention. Claims 1-6 have been examined and stand rejected. Reconsideration of Claims 1-6 is respectfully requested.

The Rejection of Claims 1-6 Under 35 U.S.C. § 103(a)

Claims 1-6 are rejected under 35 U.S.C. § 103(a) as being unpatentable over KR 1020030072855 (hereinafter "Lee") in view of U.S. Patent No. 7,008,867 (hereinafter "Lei").

The abstract of Lee describes a method comprising a first copper plating step of electroless copper plating the solder ball land of a substrate having a via hole; a first imaging step of attaching a dry film on the copper plate land, and exposing only the connection portion between the circuit and the solder ball land by exposing and developing the resultant structure; a second copper plating step of forming a lead wire for interconnecting the circuit and the solder ball land; a first strip step of removing the dry film; a first etching step of removing the copper foil from the portion which is not electroplated; a second imaging step of attaching a solder mask

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